

Productions

- ⇒ **Etching Processing**
- ⇒ **Machine Processing**
 - Laser Processing
 - Wire Cut Processing
- ⇒ **Stamping & Bending Processing**
- ⇒ **Laminate Processing**
 - Spot Welding
 - Thermal Pressure Bonding
 - Lamination for BGA Packages
- ⇒ **Surface Treatment Processing**
 - Overall Plating (Au, Ag, Pd, Ni, Solder)
 - Spot Plating (Ag)
 - Black Oxide
 - Chemical Polishing
- ⇒ **LTCC Substrate Processing**



Explanation of Production Process

(Compare Etching Process and Stamping Process.)

